

sheet layer so that the piezoelectric material provides upstanding [wall] walls separating successive channels, the walls defining opposed channel-facing surfaces, adjacent parallel channels being spaced apart from each other by a channel spacing, and electrodes being formed on [channel facing] channel-facing surfaces of the walls[,]; ; butting together said plurality of like modules; providing a channel closure sheet[, forming said channel closure sheet] formed with an array of parallel conductive tracks spaced at intervals corresponding with the channel spacing[,]; ; locating the channels in position parallel with and opposite said tracks; sealing the closure sheet to the channel walls of more than one of said like modules by forming bonds which mechanically and electrically connect each track to the respective electrodes on the [channel facing] channel-facing sides of the walls of the channel opposite the tracks [thereto]; providing nozzles respectively communicating with the channels and providing means for connecting a source of droplet liquid to the channels.

21. (Amended) [Method] The method according to Claim 20, further comprising the step of [characterized by] connecting drive current circuits to the tracks prior to forming said bonds.

22. (Amended) [Method] The method according to Claim 21, [characterized by] further comprising the steps of grouping drive current circuits together on a channel closure sheet and connecting the grouped drive current circuits via respective tracks to electrodes on the [channel facing] channel-facing walls of channels formed in different ones of said like modules.

23. (Amended) [Method] The method according to Claim 22,  
[characterized by] further comprising the step of providing said grouped drive current circuits  
in a drive chip located on the channel closure sheet.

24. (Amended) [Method] The method according to Claim 23,  
[characterized by] further comprising the step of forming said drive chip by deposition  
thereof on [a] said closure sheet.

25. (Amended) [Method] The method according to Claim 20, wherein  
said bonds are solder bonds.

26. (Amended) [Method] The method according to Claim 20, wherein  
the closure sheet is in one piece and sealed to the channel walls of all of said like modules,  
thereby spanning [the] a full width of the array.

27. (Amended) [Method] The method according to Claim 26,  
[characterized by] further comprising the step of connecting drive current circuits to the  
tracks prior to forming said bonds.

28. (Amended) [Method] The method according to Claim 27,  
[characterized by] further comprising the step of grouping drive current circuits together on a  
channel closure sheet and connecting the grouped drive current circuits via respective tracks  
to electrodes on the [channel facing] channel-facing walls of channels formed in different  
ones of said like modules.

29. (Amended) [Method] The method according to Claim 28,  
[characterized by] further comprising the step of providing said grouped drive current circuits  
in a drive chip located on the channel closure sheet.

30. (Amended) [Method] The method according to Claim 29,  
[characterized by] further comprising the step of forming said drive chip by deposition  
thereof on [a] said closure sheet.

31. (Amended) [Method] The method according to Claim 29,  
[characterized by] further comprising the step of providing on said closure sheet a plurality of  
drive chips and a set of input signal tracks, the set of input signal tracks being connected to  
each of said drive chips.

32. (Amended) [Method] The method according to Claim 31,  
[characterized by] further comprising the step of forming said plurality of drive chips by  
deposition thereof on said closure sheet.

33. (Amended) [Method] The method according to Claim 26, wherein  
said bonds are solder bonds.

In each of claims 35-45, line 1, delete "Apparatus" and substitute thereat --The  
apparatus--.

In each of claims 35 and 40, line 4, delete "channel facing" and substitute thereat --channel-facing--.

In claim 39, line 3, delete "the" and substitute thereat --a-- before the word "full".

In each of claims 60-66, line 1, delete "Apparatus" and substitute thereat --The apparatus--.

In each of claims 65 and 66, line 1, delete "51" and substitute thereat --59--.

In claim 69, line 2, delete "place" and substitute thereat --plate--.

In claim 72, lines 5 and 10, delete "the" and substitute thereat --a-- before the word "length".

In claim 72, line 13, delete "the" before the word "tops".

In claim 73, line 2, insert --of-- before the word "piezoelectric".

In claim 74, lines 1 and 6 and 10, delete "the" and substitute thereat --a-- before the word "length".

In claim 74, line 14, delete "the" before the word "tops".